

**ADHESIVES**

A COMPREHENSIVE RANGE OF ADHESIVES FOR ELECTRONIC, AUTOMOTIVE AND GENERAL MANUFACTURING INDUSTRIES.

**CONSUMABLES**

ASSEMBLY MATERIALS AND MACHINE CONSUMABLES USED IN SEMICONDUCTOR, PHOTONIC AND HYBRID ASSEMBLY ETC.

**EQUIPMENT**

ASSEMBLY, TEST AND INSPECTION EQUIPMENT FOR THE MICROELECTRONIC, ELECTRONIC, PHOTONIC AND SEMICONDUCTOR INDUSTRIES.



ADVANCED TECHNOLOGY FOR RESEARCH & INDUSTRY

# CONNECT NEWSLETTER

Welcome to the twenty first issue of our Company Newsletter "Inseto Connect", dedicated to providing information on new products, supplier & company news and technical announcements.

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## ISO 14001

Environmental awareness pays off for DELO Industrial Adhesives as they obtain ISO 14001:2015 Certification of their environmental management systems. The award demonstrates that quality, combined with chemistry and environmental awareness, can be compatible.

## Director Appointed

We are pleased to announce that Mr Jim Rhodes has recently been appointed as Inseto's new Technical Director. Since joining the Company in March 2010 as a Technical Support Engineer, Jim has been instrumental in developing the customer support philosophy of the Company, ensuring it provides industry leading levels of technical support services.

## Inseto Celebrates 30 Years

1987 was a momentous year, Margaret Thatcher was elected for a third term as Prime Minister, construction of the Channel Tunnel to France was started, the Church of England's General Synod voted to allow the ordination of women: and Tony Brown founded Inseto from the garage of his home.

This March 2017, the Company turns 30 years old; Happy Birthday Inseto!

We would like to say a BIG thank you to all our amazing staff who have worked for the Company over these years and to our loyal customers who have been the foundations of our success!

Here's to a wonderful 30 years! We've come a long way together and we are proud to celebrate this accomplishment with you.



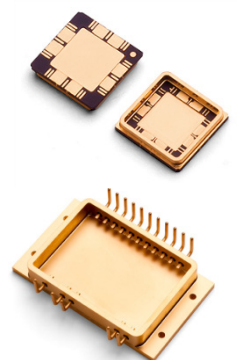
CELEBRATING  
**30** YEARS  
EST 1987

## Inseto Seal the Deal with Package Manufacturer Egide



Inseto is very pleased to announce that from May 1st, it will be the Representative for one of the world's leading-edge packaging manufacturers. Egide was founded in France in 1986 and has evolved to become a marquee name in the world of hermetic packaging for critical applications.

Egide offers both ceramic-to-metal and glass-to-metal sealed packages for high reliability applications and because it is a European manufacturer, there are no ITAR restrictions. Market segments include Aerospace & Defence, Optical and High Frequency, and industrial applications such as down-hole electronics for the oil and gas industries.



## Training for Wire Bonding

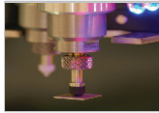
Inseto is now offering an extensive range of Certified Training Courses for Wire Bonding, including Trainer, Process, Operation and Maintenance levels.

Content can include bond theory, tool and capillary selection, bond quality control, process optimisation, machine set-up, operation, maintenance and repair, with each course customised according to exact requirements.

## Marketing Updates

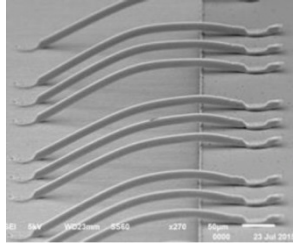
ATV, supplier of Wafer Furnaces, Vacuum Solder Reflow and Scribing equipment has recently upgraded their website: <https://www.atv-tech.com/>

Inseto has published a new version of our short-form Product Presentation; download it from our website [HERE!](#)



## Equipment News

### K&S Ball & Wedge Bonder



Kulicke & Soffa (K&S) has developed a comprehensive solution for Fine Aluminum (Wedge-to-Wedge) Wire Bonding – with the new launched VitaCap™ Series of Capillaries and IConnPS PLUS™ and ConnX PLUS Ball Bonder. Wire size range from 0.6 to 2mil.

VitaCap™ is made from K&S' leading ITA™ ceramics material, engineered for high quality Aluminum wedge bond and wedge tail formation on any wire direction. Its unique features fit well with IConnPS PLUS™ and ConnX PLUS Ball Bonders' special wedge-to-wedge feature.

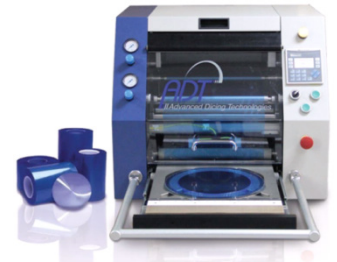
Together, they deliver an innovative wire bonding platform for applications that uses fine Aluminum wire. The key advantages of this comprehensive solution are:

- Flexibility of using the Ball Bonder for either Aluminum or Gold wire
- Improved productivity resulting in lower cost of ownership over traditional wedge bonders
- Applicable for low loop applications



### New Semiautomatic Wafer Mounter

The 967 Semiautomatic Wafer Mounter from ADT is a small footprint user friendly system for automatic bubble free mounting for wafers up to 200mm, onto either standard blue or UV tapes.



The 967 provides fast, accurate mounting, avoiding the risks associated with manual systems. Once set, the sequence is used for each wafer, thus ensuring high quality and consistent results.

### Atmospheric Plasma System

With up to 1000 watts of power, the Atmospheric Plasma System is perfect for cleaning and activating surfaces prior to bonding, printing or other assembly processes.



The system is machine mountable and designed for easy integration into new or existing assembly lines.

The plasma nozzle is capable of producing plasma stream up to 25mm wide, with a treatment distance of up to 40mm from the plasma head, providing consistent and repeatable results.



## Adhesives News

### New Electronic Adhesive for Delicate Structures

DELO has introduced a new electronic adhesive featuring very thin and high walls at the same time.

DELOMONOPOX GE7985 has been developed for automotive and industrial applications requiring high walls at the same time.

DELOMONOPOX GE7985 has been developed for automotive and industrial applications requiring high reliability in combination with miniaturized designs.



The new adhesive has smaller fillers than previous products of the company's "dam-and-fill" range, allowing it to be applied with needles of a minimum diameter of 250 µm, which is important given the increasing miniaturization in electronics. Thanks to an exceptionally high viscosity of 160,000 mPas, the adhesive additionally provides high flow resistance and an aspect ratio of 2.5. This means that the height of an adhesive bead can be more than twice its width, without the bead collapsing.

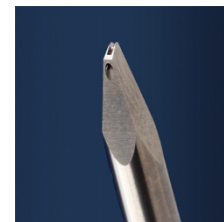
The adhesive cures under heat with variable conditions in terms of time and temperature, for example, 20 minutes at 150 °C or 90 minutes at 125 °C. Thanks to the adhesive's flow resistance, the aspect ratio does not change during this process, so the height of the adhesive bead remains the same after heat curing.

In addition, DELOMONOPOX GE7985 contains zero SVHC raw materials



## Materials News

### Die & Wire Bonding Tools



Inseto is now providing a full range of advanced wire and die bonding tools from world leading manufacturers.

Products include ultrasonic wedge tools for small wire & ribbon bonding, capillaries for ball bonding, die attach collets and die bond tools, with custom tools also available on request.

The product range is designed to suit all major brands of die & wire bonding equipment, including K&S, Hesse, ASM, MRSI & Delvotec etc.

#### See us at the following events in 2017:

- IMAPS-Nordic Conference, 18-20 June, Sweden
- Power Electronics Conference, 4-5 July, Loughborough
- UK Semiconductors, 12-13 July, Sheffield
- FAST - Fastening & Assembly Solutions, 21 Sept., Duxford
- Engineering Design Show, 18-19 October, Coventry
- IMAPS-UK RelPack, 30 November, Daresbury

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